

1.9mm Round Subminiature Axial Infrared LEDS IR91-21C



Features

- Small double-end package
- High reliability
- Low forward voltage
- Good spectral matching to Si photodetector
- Pb free
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Descriptions

IR91-21C is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with spherical top view lens. The device is spectrally matched with silicon photodiode and phototransistor.

Applications

- PCB mounted infrared sensor
- Infrared emitting for miniature light barrier
- Floppy disk drive
- Optoelectronic switch
- Smoke detector

Device Selection Guide

Part Category	Chip Material	Lens Color
IR	GaAlAs	Water Clear

Technical drawing of a photoresistor (photoresistor) showing two views: a top view and a side view.

Top View Dimensions:

- Package width: 2.5 ± 0.1
- Lead diameter: 0.5 ± 0.1
- Lead length: 2.0 ± 0.2
- Central circular area diameter: $\phi 1.9 \pm 0.2$
- Lead 1 is marked with a "Color mark".

Side View Dimensions:

- Package height: 2.7 ± 0.1
- Lead thickness: 0.15 ± 0.05
- Package height (excluding leads): 1.4 ± 0.1
- Radius of top edge: $R0.8 \pm 0.1$
- Lead thickness (top view): 0.65 ± 0.1
- Lead thickness (side view): 1.3 ± 0.1
- Lead thickness (bottom view): 0.75 ± 0.1

Polarity Diagram:

① Cathode
② Anode

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Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Units
Continuous Forward Current	I _F	65	mA
Peak Forward Current	I _{FP}	1.0	A
Reverse Voltage	V _R	5	V
Operating Temperature	T _{opr}	-25 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	°C
Soldering Temperature *1	T _{sol}	260	°C
Power Dissipation at(or below) 25°C Free Air Temperature	P _d	130	mW

Notes: *1: Soldering time ≤ 5 seconds.

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Radiant Intensity	I _e	I _F =20mA	3.0	5.0		mW /sr
Peak Wavelength	λ _p	I _F =20mA	--	940	--	nm
Spectral Bandwidth	Δ λ	I _F =20mA	--	45	--	nm
Forward Voltage	V _F	I _F =20mA	--	1.2	1.5	V
Reverse Current	I _R	V _R =5V	--	--	10	μ A
View Angle	2 θ 1/2	I _F =20mA	--	25	--	deg

Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs.
Ambient Temperature

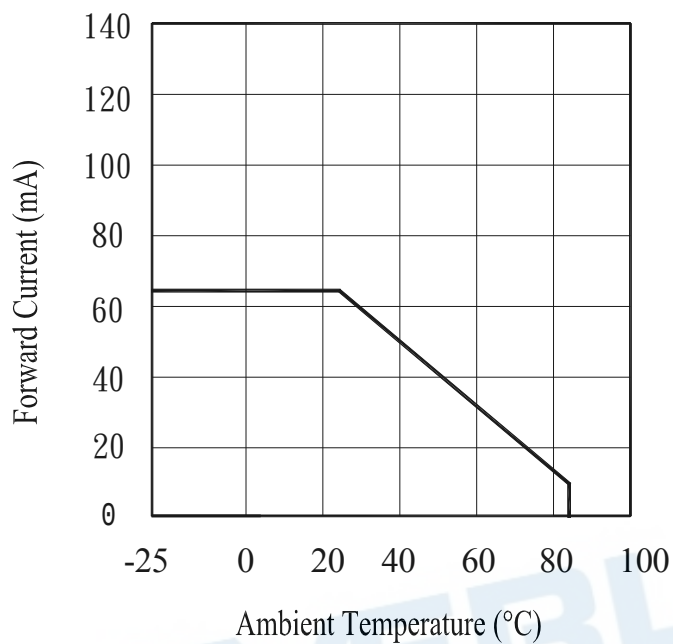


Fig.2 Spectral Distribution

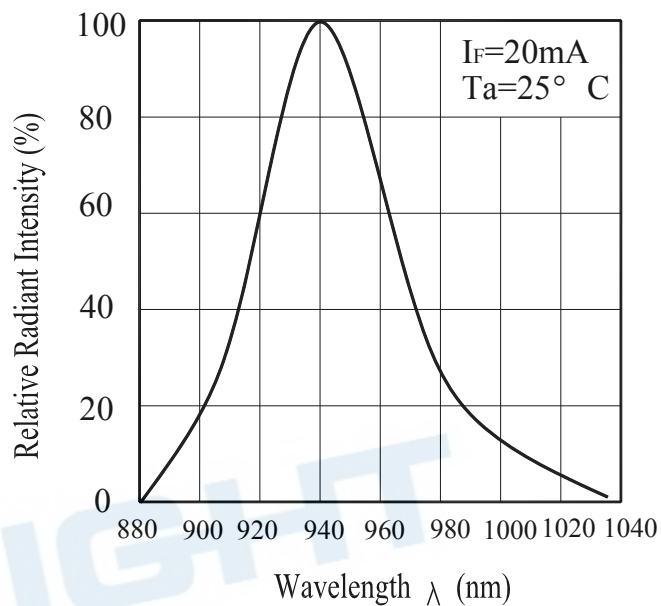


Fig.3 Forward Current vs. Forward Voltage

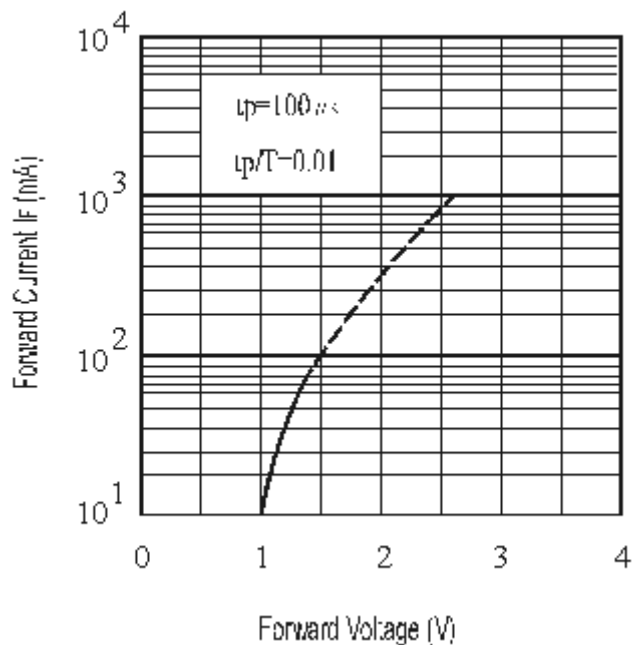
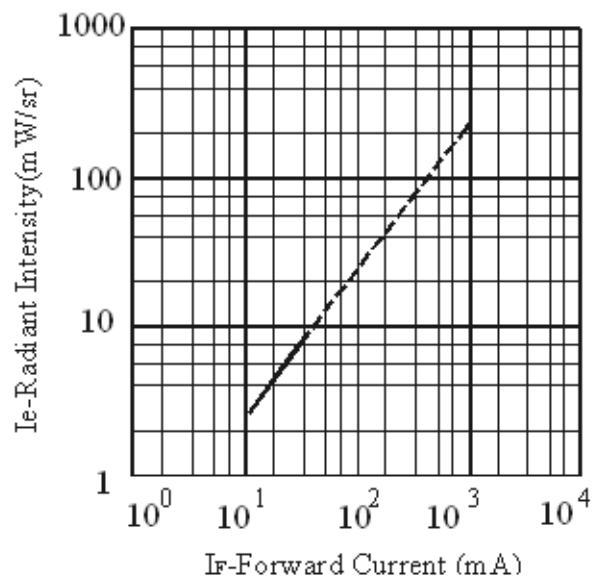
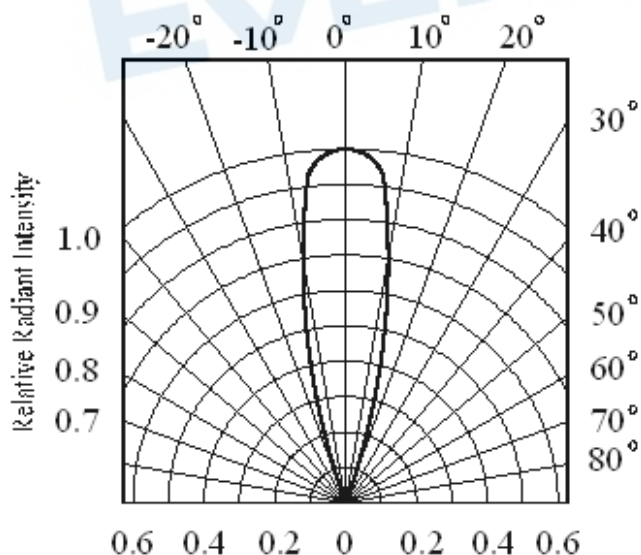


Fig.4 Relative Intensity vs. Forward Current



Typical Electro-Optical Characteristics Curves

Fig.5 Relative Radiant Intensity vs. Angular Displacement



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDss should be kept at 30°C or less and 90%RH or less.

2.3 The LEDss should be used within a year.

2.4 After opening the package, the LEDss should be kept at 30°C or less and 70%RH or less.

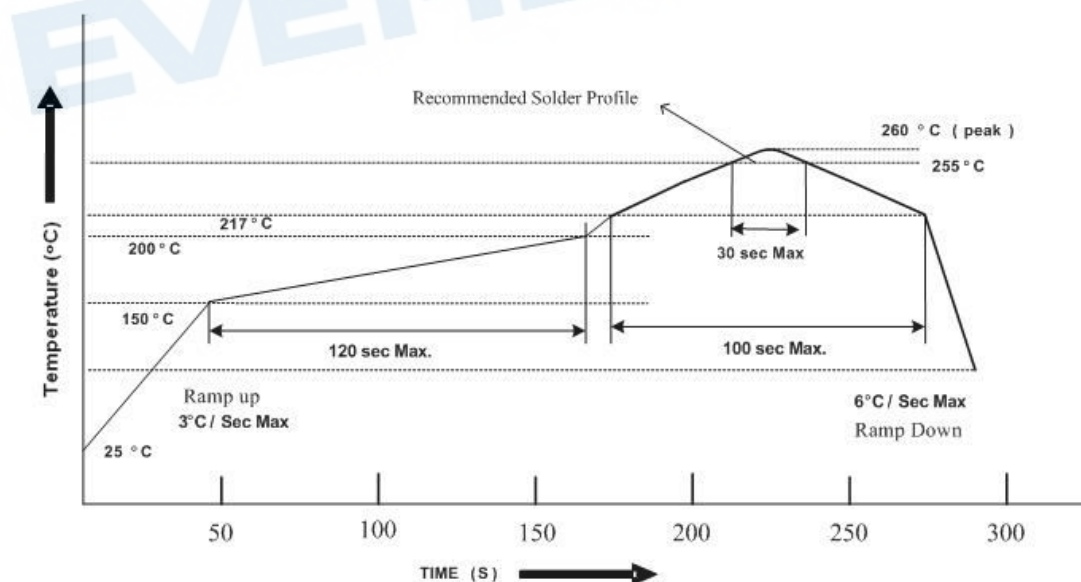
2.5 The LEDss should be used within 168 hours (7 days) after opening the package.

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDss have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : $60\pm5^{\circ}\text{C}$ for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDss during heating.

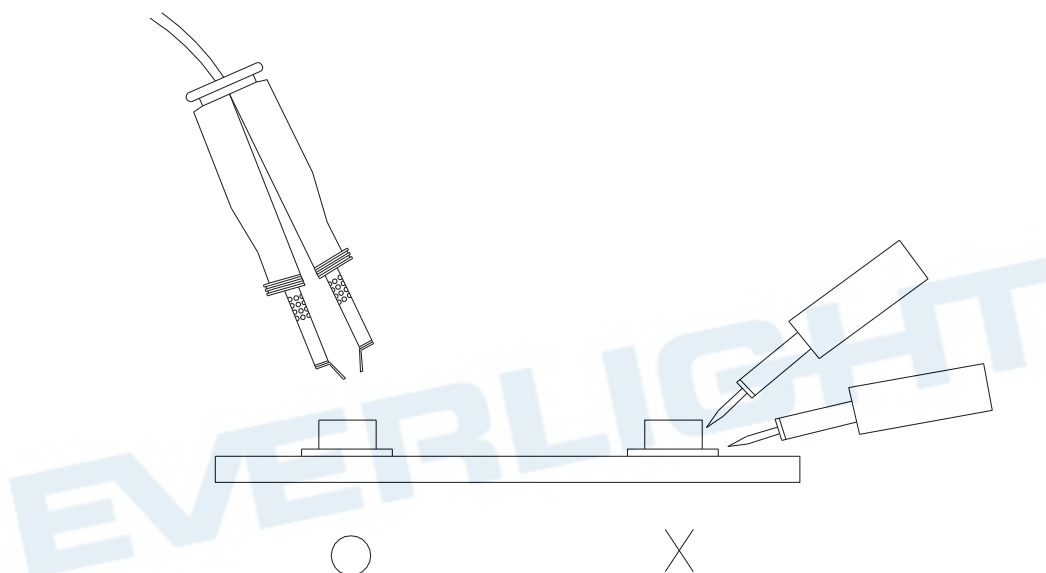
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDSs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDSs will or will not be damaged by repairing.



Packing Quantity Specification

1000PCS/1Bag

Label Form Specification



CPN: Customer's Production Number

P/N : Production Number

QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

DISCLAIMER

1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
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